

IN THE CLAIMS:

All of the pending claims 1 through 4 are presented below. This listing of claims will replace all prior versions and listings of claims in the application.

1. (Previously Presented) A method for connecting a horizontally stacked plurality of primary integrated circuit packages on a substrate having a plurality of circuits thereon, each primary integrated circuit package having a plurality of outer leads and having a plurality of sides, using a cage having an open side, comprising:
providing a cage enclosing at least two sides of the plurality of sides of each primary integrated circuit package of the stacked plurality of primary integrated circuit packages; and
attaching the cage to the substrate, the cage connecting at least one outer lead of the plurality of outer leads of the stacked plurality of primary integrated circuit packages to at least one conductive bus of a plurality of spaced transverse conductive buses.

2. (Previously Presented) The method of claim 1, wherein providing the cage further comprises:

providing a cage enclosing more than the at least two sides of the plurality of sides of each primary integrated circuit package of the stacked plurality of primary integrated circuit packages; and
attaching the cage to the substrate, the cage connecting the at least one outer lead of the plurality of outer leads of the stacked plurality of primary integrated circuit packages to the at least one conductive bus of the plurality of spaced transverse conductive buses.

3. (Previously Presented) A method for connecting a horizontally stacked plurality of primary integrated circuit packages on a substrate having a plurality of circuits thereon, each primary integrated circuit package having a plurality of outer leads and having a plurality of sides, comprising:

providing a cage enclosing at least two sides of the plurality of sides of each primary integrated circuit package of the stacked plurality of primary integrated circuit packages; and

attaching the cage to the substrate, the cage connecting at least one outer lead of the plurality of outer leads of the stacked plurality of primary integrated circuit packages to at least one conductive bus of a plurality of spaced transverse conductive buses.

4. (Previously Presented) A method for connecting a horizontally stacked plurality of primary integrated circuit packages on a substrate having a plurality of circuits thereon, each primary integrated circuit package having a plurality of outer leads and having a plurality of sides, comprising:

providing a cage enclosing at least three sides of the plurality of sides of each primary integrated circuit package of the stacked plurality of primary integrated circuit packages; and attaching the cage to the substrate using one of adhesive and snap pins fitting in holes in the substrate, the cage connecting at least one outer lead of the plurality of outer leads of the stacked plurality of primary integrated circuit packages to at least one conductive bus of a plurality of spaced transverse conductive buses, with a portion of a semi-continuous flexible tape located within the cage.